## G4L3-SD1-LAX3

HPC/AI Server - 4U DP HGX™ H200 8-GPU DLC









## **Features**

- Liquid-cooled NVIDIA HGX™ H200 8-GPU
- CPU+GPU direct liquid cooling solution with leak detection
- 900GB/s GPU-to-GPU bandwidth with NVLink® and NVSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series.
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA BlueField®-3 DPUs and ConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCle Gen3 x2 and x1 interface
- 8 x 2.5" Gen5 NVMe/SATA hot-swap bays
- 4 x FHHL dual-slot PCle Gen5 x16 slots
- 8 x FHHL single-slot PCle Gen5 x16 slots
- 4+4 3000W 80 PLUS Titanium redundant power supplies

## **Specification**

Dimensions	4U (W447 x H175.3 x D900 mm)	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN
Motherboard	MSB3-PE0		
Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 8 x SXM GPUs	Backplane Board	Speed and bandwidth: PCle Gen5 x4 or SATA 6Gb/s
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 385W	TPM	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010
Socket	2 x LGA 4677 (Socket E)	Power Supply	4+4 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Chipset	Intel® C741 Chipset	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
Memory	8-Channel DDR5 RDIMM, 32 x DIMM slots Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)		
LAN	2 x 10Gb/s LAN ports (1 x Intel® X710-AT2) - Support NCSI function 1 x 10/100/1000 management LAN	OS Support	Windows Server, Red Hat Enterprise Linux Server, VMware ESXi, SUSE Linux Enterprise, Ubuntu Server, Citrix Hypervisor
Video	Integrated in ASPEED® AST2600 - 1 x VGA port		
Storage	Front hot-swap:	0	, , , , ,
	8 x 2.5" Gen5 NVMe/SATA Internal M.2:	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing)
	1 x M.2 (2280/22110), PCIe Gen3 x2		Non-operating temperature: -40°C to 60°C
	1 x M.2 (2280/22110), PCIe Gen3 x1		Non-operating humidity: 20%-95% (non-condensing)
RAID	Intel® SATA RAID 0/1/10/5 Support optional RAID add-in cards	Packaging Content	1 x G4L3-SD1-LAX3, 1 x CPU cold plate loop, 6 x Carriers, 1 x L-shape Rail kit
Expansion Slots	4 x FHHL dual-slot PCIe Gen5 x16 slots 8 x FHHL single-slot PCIe Gen5 x16 slots	Part Numbers	Barebone w/ NVIDIA module: 6NG4L3SD1DR000LBX3*



## Learn more at https://www.GIGABYTE.com/enterprise

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